#### 2.0x1.25mm SMD CHIP LED LAMP



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE

**DEVICES** 

Part Number: KPTK-2012TGC

GREEN

#### **Features**

- •2.0mmx1.25mm SMT LED. 0.75mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACK LIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS/REEL.
- •MOISTURE SENSITIVITY LEVEL: LEVEL 4.
- •RoHS COMPLIANT.

#### **Description**

The Green source color devices are made with InGaN on SiC Light Emitting Diode.

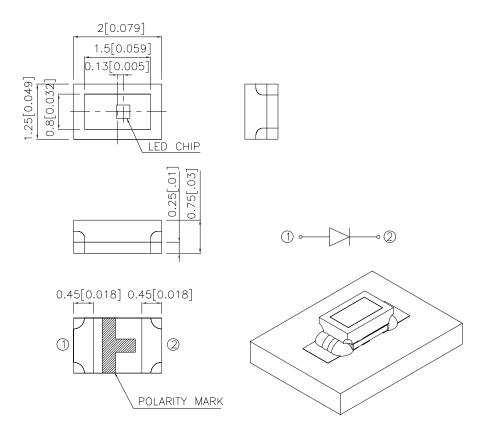
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electri-

cally grounded.

#### **Package Dimensions**



#### Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.1(0.004")$  unless otherwise noted.
- Specifications are subject to change without notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.





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#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcc @ 20	,	Viewing Angle[1]
			Min.	Тур.	201/2
KPTK-2012TGC	GREEN (InGaN)	WATER CLEAR	70	150	100°

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2.Luminous Intensity / Luminous Flux: +/-15%.

#### Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	505		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	507		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	32		nm	IF=20mA
С	Capacitance	Green	38		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.2	3.8	V	IF=20mA
lR	Reverse Current	Green		10	uA	VR = 5V

#### Notes:

- 1. Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

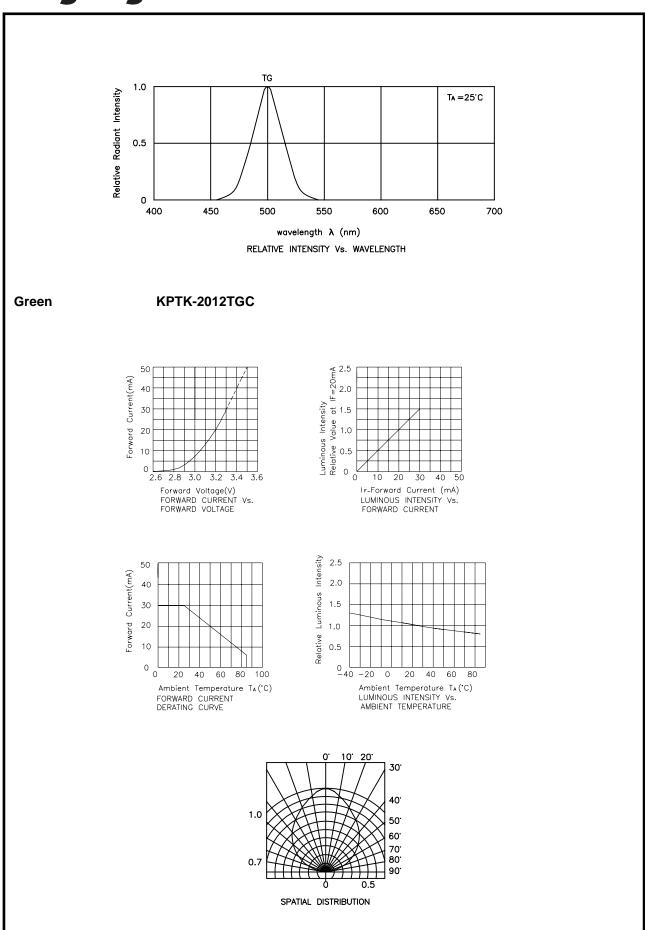
#### Absolute Maximum Ratings at Ta=25°C

Parameter	Green	Units	
Power dissipation	114	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	100	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

#### Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

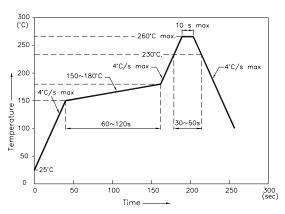
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### KPTK-2012TGC

Reflow Soldering Profile For Lead-free SMT Process.



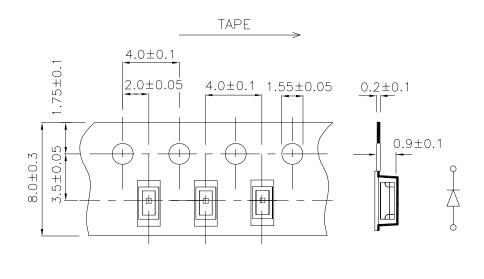
NOTES:

- 1.We recommend the reflow temperature  $245^{\circ}\text{C}(+/-5^{\circ}\text{C})$ .The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

### VRecommended Soldering Pattern (Units: mm; Tolerance: ±0.1)



### Tape Specifications (Units: mm)



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